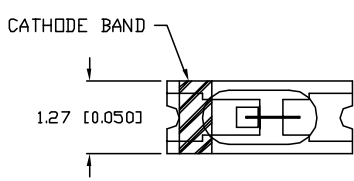
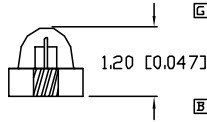
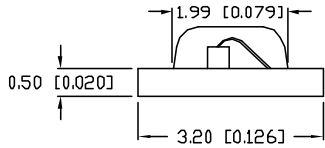
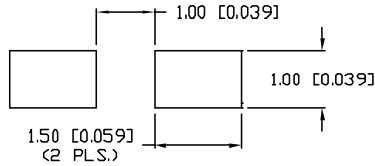


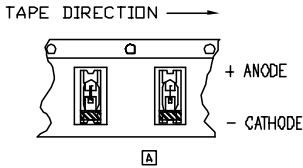
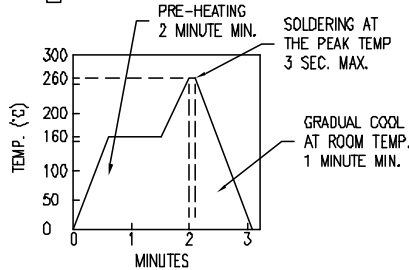
UNCONTROLLED DOCUMENT



SOLDER PAD LAYOUT



REFLOW SOLDER CHART



PART NUMBER		REV.
CCL-LX45IT		H
REV.	E.C.N. NUMBER AND REVISION COMMENTS	DATE
A	ADDED TAPE AND REEL SPEC./	11-20-95
B	E.C.N. #10105./	12-18-95
C	E.C.N. #10143./	4-8-96
D	E.C.N. #10176./	5-30-96
E	E.C.N. #10BRDR. & REDRAWN.	11-9-98
F	E.C.N. #10511./ ADDED SOLDER CHART.	4-28-99
G	E.C.N. #10524./ CHANGED HEIGHT.	6-17-99
H	E.C.N. #11148.	12.04.06

ELECTRO-OPTICAL CHARACTERISTICS  $T_A=25^{\circ}\text{C}$   $I_f=20\text{mA}$

PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		635 (RED)		nm	
FORWARD VOLTAGE		2.1	2.5	V <sub>f</sub>	
REVERSE VOLTAGE	5.0			V <sub>r</sub>	I <sub>f</sub> =100μA
AXIAL INTENSITY		7.2		mcd	I <sub>f</sub> =20mA
VIEWING ANGLE		180		2x theta	
EMITTED COLOR:	RED				
EPOXY LENS FINISH:	RED TRANSPARENT				

LIMITS OF SAFE OPERATION AT 25°C

PARAMETER	MAX	UNITS
PEAK FORWARD CURRENT*	800	mA
STEADY CURRENT	30	mA
POWER DISSIPATION	130	mW
DERATE FROM 25°C	-2.4	mW/°C
OPERATING TEMP.	-30 TO +80	°C
STORAGE TEMP.	-40 TO +120	°C

\*  $t < 10\mu\text{s}$

\*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.038), XX=±0.5 (±0.020), XXX=±0.25 (±0.010), XXXX=±0.127 (±0.005).

LEAD SIZE=±0.05 (0.002), LEAD LENGTH=±0.75 (±0.030), MIN=+DECIMAL PRECISION MAX=-0.00 -DECIMAL PRECISION

UNCONTROLLED DOCUMENT

REV. H	PART NUMBER CCL-LX45IT
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**CONFIDENTIAL INFORMATION**  
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CERAMIC CHIP, SURFACE MOUNT LED,  
RED TRANSPARENT, TAPE AND REEL.

**RELIABILITY NOTE**  
OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

DRAWN BY: JC	CHECKED BY:	APPROVED BY:	DATE: 11.20.95 PAGE: 1 OF 1 SCALE: N/A
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